

RELIABILITY REPORT
FOR
MAX4247AUB+
PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX4247AUB+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description**A. General**

The MAX4245/MAX4246/MAX4247 family of low-cost op amps offer rail-to-rail inputs and outputs, draw only 320 μ A of quiescent current, and operate from a single +2.5V to +5.5V supply. For additional power conservation, the MAX4245/MAX4247 offer a low-power shutdown mode that reduces supply current to 50nA, and puts the amplifiers' outputs in a high-impedance state. These devices are unity-gain stable with a 1MHz gain-bandwidth product driving capacitive loads up to 470pF. The MAX4245/MAX4246/MAX4247 family is specified from -40°C to +125°C, making them suitable for use in a variety of harsh environments, such as automotive applications. The MAX4245 single amplifier is available in ultra-small 6-pin SC70 and space-saving 6-pin SOT23 packages. The MAX4246 dual amplifier is available in 8-pin, SO, SOT23 and μ MAX® packages. The MAX4247 dual amplifier comes in a tiny 10-pin μ MAX package.

II. Manufacturing Information

A. Description/Function:	Ultra-Small, Rail-to-Rail I/O with Disable, Single/Dual-Supply, Low-Power Op Amps
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	California or Texas
E. Assembly Location:	Philippines, Thailand, Malaysia
F. Date of Initial Production:	April 27, 2001

III. Packaging Information

A. Package Type:	10-pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-2501-0166
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	180°C/W K.
Single Layer Theta Jc:	41.9°C/W
L. Multi Layer Theta Ja:	113.1°C/W
M. Multi Layer Theta Jc:	41.9°C/W

IV. Die Information

A. Dimensions:	80X24 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{1000 \times 4340 \times 232 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 0.91 \times 10^{-9}$$

$\lambda = 0.91$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.01 @ 25C and 0.26 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot I2N1AQ001B, D/C 0111)

The OX58-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4247AUB+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	98	0	D2N0CQ003T, 0636
	Biased	& functionality	134	0	I2N0AQ001D, 0226
	Time = 1000 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.